

ABSTRACT OF THE DISCLOSURE

A package structure of a solid-state image sensor having a solid-state image sensor chip and a color filter stuck on a light receiving surface of the chip. The package structure includes a vessel for packaging the solid-state image sensor chip. An optically transparent protection plate is attached to the vessel to cover the light receiving surface of the chip. A resin layer is arranged between the chip and the protection plate to absorb light having a predetermined wavelength.